

SUBMINIATURE SOLID STATE LAMP

Part Number: AM27SYCK03 Super Bright Yellow

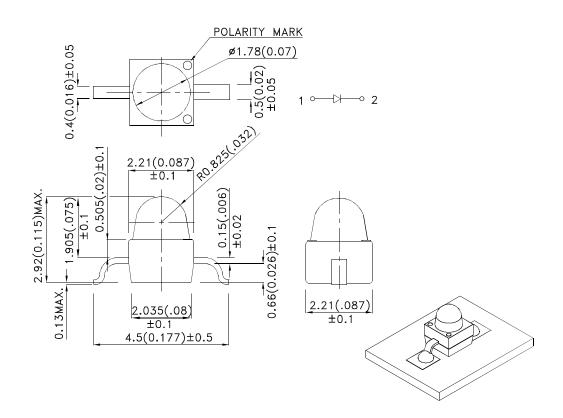
Features

- Subminiature package.
- · Gull wing.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAD1303 **REV NO: V.9** DATE: APR/14/2011 PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000417

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
AM27SYCK03	Super Bright Yellow (AlGaInP)	Water Clear	1400	2300	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	I==20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I==20mA
IR	Reverse Current	Super Bright Yellow		10	uA	V _R =5V

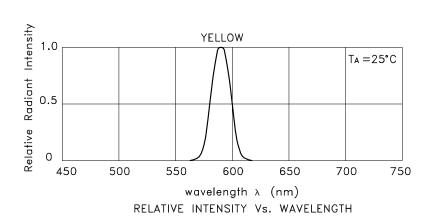
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

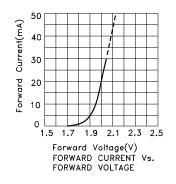
Parameter	Super Bright Yellow		
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	175	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

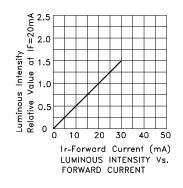
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

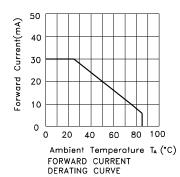
SPEC NO: DSAD1303 **REV NO: V.9** DATE: APR/14/2011 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000417

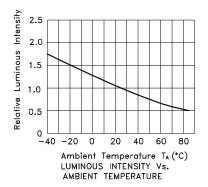


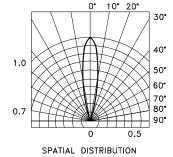
Super Bright Yellow AM27SYCK03











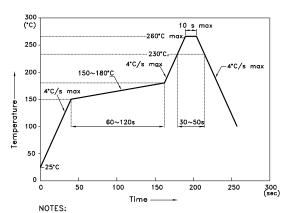
 SPEC NO: DSAD1303
 REV NO: V.9
 DATE: APR/14/2011
 PAGE: 3 OF 5

 APPROVED: WYNEC
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AM27SYCK03

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



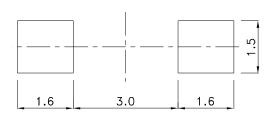
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

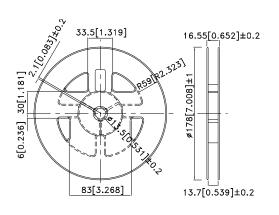
 3.Number of reflow process shall be 2 times or less.

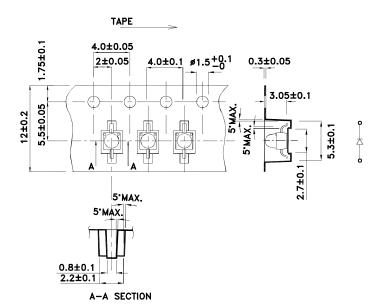
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

Reel Dimension

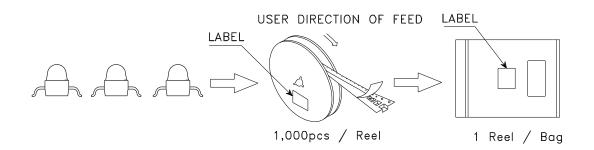


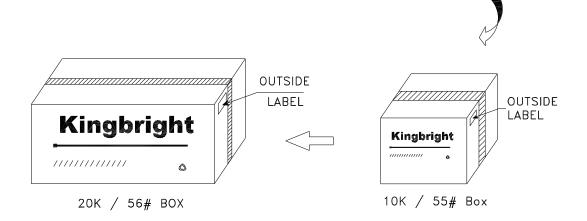


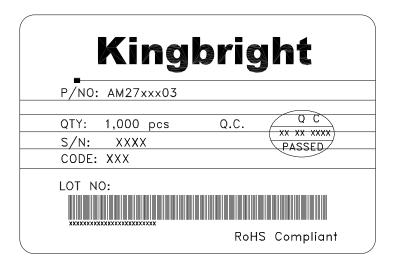
SPEC NO: DSAD1303 **REV NO: V.9** DATE: APR/14/2011 PAGE: 4 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000417

PACKING & LABEL SPECIFICATIONS

AM27SYCK03







SPEC NO: DSAD1303 APPROVED: WYNEC REV NO: V.9 CHECKED: Allen Liu DATE: APR/14/2011 DRAWN: J.Yu PAGE: 5 OF 5 ERP: 1202000417